

In the Specification:

N.B. Please replace paragraph page 92, line 19 with new paragraph page 92, line 19, shown below.

However, materials such as aluminum and oxide can be used for the MEMS structures, as these have lower Young's modulus by a wide margin (69x10⁹ instead of 170x10⁹), aluminum has much lower resistance, and the micromechanical structures can be fabricated out of the same steps which are normally used for the metal interconnects and intermetal dielectrics. Unfortunately, most processes tend to leave quite large residual biases in these materials. But fortunately, the direction of the biases for different layers tend to be different. By careful tailoring of multi-layer films and their biases, and one or more additional process steps, the sum of the residual stresses can be reduced to a very low value.